



Material Content Data Sheet



Sales Product Name		IFX20002MB V33		Issued		29. August 2013		
MA#		MA001042676						
Package		PG-SCT595-5-1		Weight*		13.90 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.328	2.36	2.36	23574	23574
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		87	
	non noble metal	titanium	7440-32-6	0.006	0.04		435	
	non noble metal	chromium	7440-47-3	0.018	0.13		1305	
	non noble metal	copper	7440-50-8	6.019	43.32	43.50	433051	434878
wire	noble metal	gold	7440-57-5	0.027	0.19	0.19	1908	1908
encapsulation	organic material	carbon black	1333-86-4	0.055	0.39		3941	
	plastics	brominated resin	-	0.068	0.49		4926	
	inorganic material	antimonytrioxide	1309-64-4	0.137	0.99		9851	
	plastics	epoxy resin	-	1.246	8.96		89647	
	inorganic material	silicondioxide	60676-86-0	5.340	38.42	49.25	384201	492566
leadfinish	non noble metal	tin	7440-31-5	0.335	2.41	2.41	24133	24133
plating	noble metal	silver	7440-22-4	0.142	1.02	1.02	10181	10181
glue	plastics	epoxy resin	-	0.031	0.22		2233	
	noble metal	silver	7440-22-4	0.146	1.05	1.27	10527	12760
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com